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ABSTRACT

A method for polishing a wafer effectively preventing a sag in an outer peripheral portion of a wafer and a polishing pad for polishing a wafer preferably used in the method for polishing a wafer are provided. The method for polishing a wafer comprises the step of: mirror-polishing a wafer with a main surface of the wafer being in contact with a polishing pad of non-woven fabric impregnated with resin, wherein a ratio of surface roughness of the polishing pad to compressibility thereof {surface roughness Ra (μm)/compressibility (%)} is 3.8 or more.